

	<b>Hits</b>	<b>Search Text</b>	<b>DBs</b>
<b>1</b>	4	((resist or photoresist) near36 (opening or hole or groove or recess) near39 (expos\$4 or imag\$4 or irradiat\$4)) and (resin\$4 same (water\$5soluble) same (thicken\$5 or enhanc\$4 or smooth\$6 or shrinking or coat\$4) same (cationic or ester or (quaternary near5 amide)) same (surfactant)) and (surfactant same (cationic or anionic or amphoteric))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
<b>2</b>	4	((resist or photoresist) near22 pattern near36 (opening or hole or groove or recess) near39 (expos\$4 or imag\$4)) and (resin\$4 same (water\$5soluble) same (thicken\$5 or enhanc\$4 or smooth\$6 or shrinking or coat\$4) same (cationic or ester or (quaternary near5 amide)) same (surfactant)) and (surfactant same (cationic or anionic or amphoteric))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	<b>Hits</b>	<b>Search Text</b>	<b>DBs</b>
<b>3</b>	0	((resist or photoresist) near22 pattern near36 (opening or hole or groove or recess) near39 (expos\$4 or imag\$4)) and (resin\$4 same (water\$5soluble) same (thicken\$5 or enhanc\$4 or smooth\$6 or shrinking or coat\$4) same (cationic or ester or (quaternary near5 amide)) same (surfactant)) and (surfactant same (cationic or anionic or amphoteric))	USOCR
<b>4</b>	0	((resist or photoresist) near29 (opening or recess or groove or via or hole) near39 (expos\$4 or imag\$4)) and (resin\$4 same (water\$5soluble) same (thicken\$5 or enhanc\$4 or smooth\$6) same (thickness or micron or Angstrom)) and (surfactant same (cationic or anionic or amphoteric))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
<b>5</b>	5	((resist or photoresist) near29 (opening or recess or groove or via or hole) near39 (expos\$4 or imag\$4)) and (resin\$4 same (water\$5soluble) same (thicken\$5 or enhanc\$4 or smooth\$6) same (thickness or micron or Angstrom))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB